

N-Channel Enhancement Mode MOSFET

Primary characteristics			
Symbol	Parameter	Value	Unit
I_D	Continuous drain current	21	A
V_{DSS}	Drain source voltage	60	V
$R_{DS(on)}$	Static drain-source on-resistance	35	$\text{m}\Omega$ MAX

Case dimensions															
PDFN3x3-8L															
Unit		A	B	C	D	E	F	G	H	I	J	K	L	M	N
mm		MIN 3.1	2.9	0.65	0.2	0	0	0.55	0.2	0.7	0.1	3.15	0.2	2.35	1.5
		MAX 3.1	3.1	0.85	0.4	0.1	0.1	0.75	0.4	1.1	0.2	3.45	0.4	2.55	1.9

Maximum ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Value	Unit
Drain-source voltage	V_{DSS}	60	V
Gate-source voltage	V_{GSS}	± 20	V
Continuous drain current ($T_C=25^\circ\text{C}$)	I_D	21	A
Continuous drain current ($T_C=100^\circ\text{C}$)		13	
Continuous drain current ($T_A=25^\circ\text{C}$) ¹⁾		7.2	
Continuous drain current ($T_A=100^\circ\text{C}$) ¹⁾		4.5	
Pulsed drain current ($t_p=10\mu\text{s}$, $T_c=25^\circ\text{C}$)	I_{DM}	84	A
Pulsed drain current ($t_p=10\mu\text{s}$, $T_A=25^\circ\text{C}$)		60	
Single pulse avalanche energy ³⁾	E_{AS}	6.0	mJ
Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	18	W
Power Dissipation ($T_A=25^\circ\text{C}$) ¹⁾		2.0	
Operating junction temperature range	T_J , T_{STG}	-55 ~ 150	°C

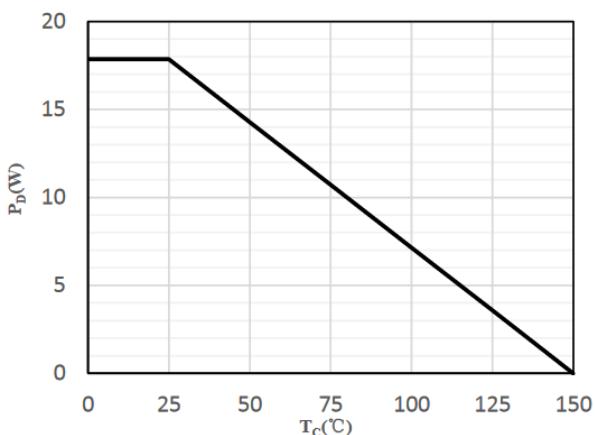
Thermal characteristics						
Characteristic	Test condition	Symbol	Min.	Value Typ.	Max.	Unit
Thermal resistance junction-case	-	R _{θJC}	-	-	7.0	°C/W
Thermal resistance junction-ambient ¹⁾		R _{θJA}	-	54	60	°C/W
Electrical characteristics ($T_A = 25^\circ\text{C}$)						
Characteristic	Test condition	Symbol	Min.	Value Typ.	Max.	Unit
Drain-source breakdown voltage	V _{GS} =0V, I _D =250μA	V _{DSS}	60	-	-	V
Zero gate voltage drain current	V _{DS} =60V, V _{GS} =0V	I _{DSS}	-	-	1.0	μA
Gate body leakage current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Gate threshold voltage	V _{DS} =V _{GS} , I _D =250μA	V _{GS(TH)}	1.0	1.5	3.0	V
Drain-source on-state resistance ²⁾	V _{GS} =10V, I _D =10A	R _{D(S)}	-	21	25	mΩ
	V _{GS} =4.5V, I _D =10A		-	27	35	
Gate resistance	V _{GS} =0V, f=1.0MHz	R _G	-	3.8	-	Ω
Dynamic electrical characteristics						
Characteristic	Test condition	Symbol	Min.	Value Typ.	Max.	Unit
Input capacitance	V _{DS} =25V V _{GS} =0V f=1.0MHz	C _{ISS}	-	570	-	pF
Output capacitance		C _{OSS}	-	186	-	
Reverse transfer capacitance		C _{rss}	-	23	-	
Switching characteristics						
Characteristic	Test condition	Symbol	Min.	Value Typ.	Max.	Unit
Turn ON delay time	V _{DD} =30V V _{GS} =15V I _D =15A R _G =3.3Ω	t _{d(ON)}	-	3.0	-	ns
Turn ON rise time		t _r	-	37	-	
Turn OFF delay time		t _{d(OFF)}	-	14	-	
Turn OFF fall time		t _f	-	30	-	
Total gate-charge	V _{DD} =40V V _{GS} =10V I _D =10A	Q _G	-	14.5	-	nC
Gate to source charge		Q _{GS}	-	2.6	-	
Gate to drain (Miller) charge		Q _{GD}	-	2.9	-	
Source-drain diode characteristics						
Characteristic	Test condition	Symbol	Min.	Value Typ.	Max.	Unit
Diode forward voltage ²⁾	I _{SD} =10A, V _{GS} =0V, T _J =25°C	V _{SD}	-	0.9	1.2	V
Reverse recovery time	I _F =10A, V _R =30V d _i /d _t =100A/μs	t _{rr}	-	24.8	-	ns
Reverse recovery charge		Q _{rr}	-	15.7	-	nC

Notes:

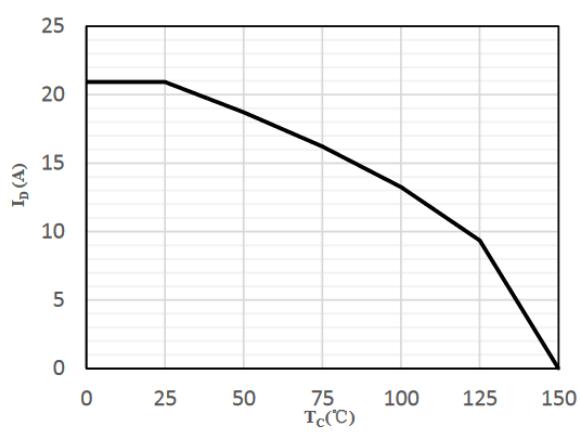
- 1) The data tested by surface mounted on a 1.0 inch² FR-4 board with 2oz copper
- 2) The data tested by pulsed, pulse width ≤300μs, duty cycle ≤2%
- 3) The E_{AS} data shows max. rating. The test condition is V_{DD}=30V, L=0.5mH, V_{GS}=10V

Typical characteristics

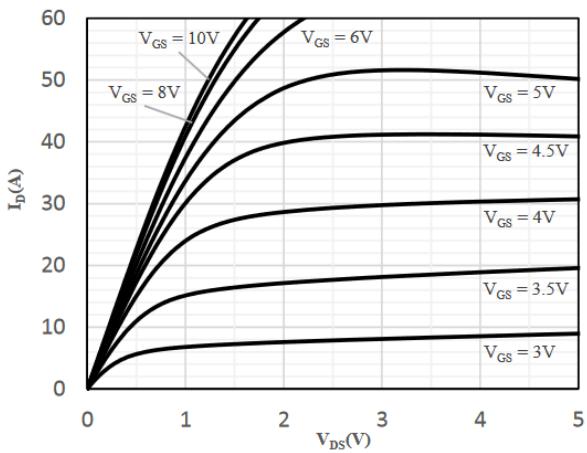
Power dissipation



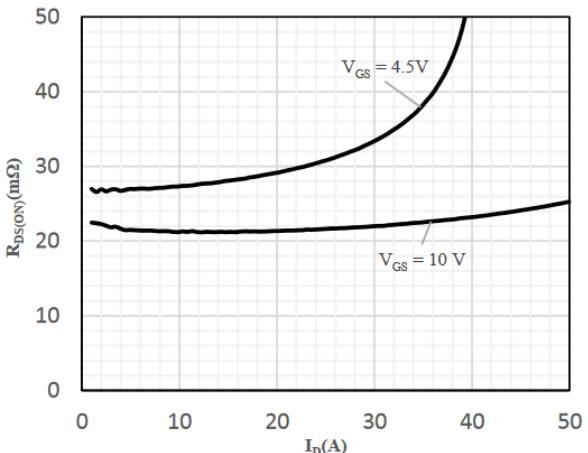
Drain current



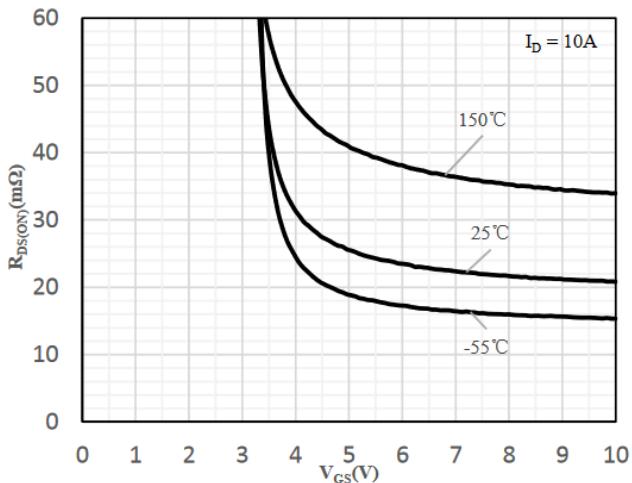
Typical output characteristics



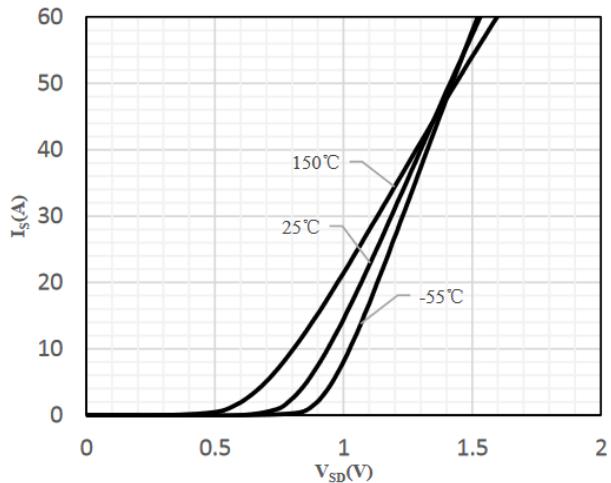
ON-resistance vs. drain current and gate voltage

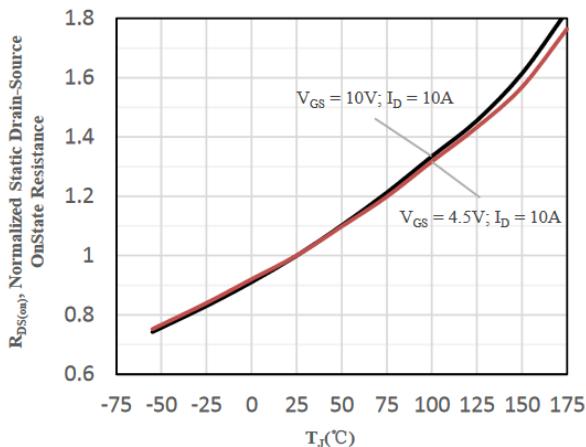
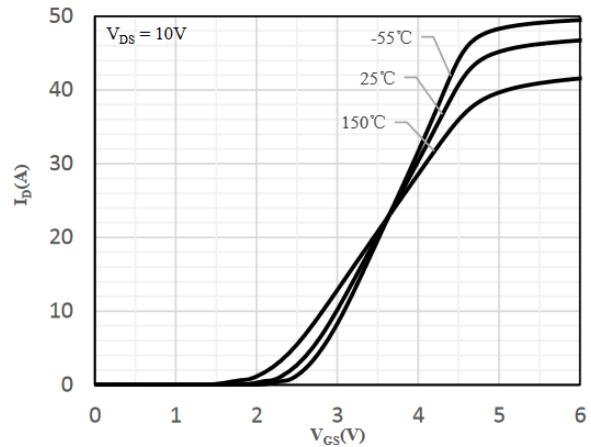
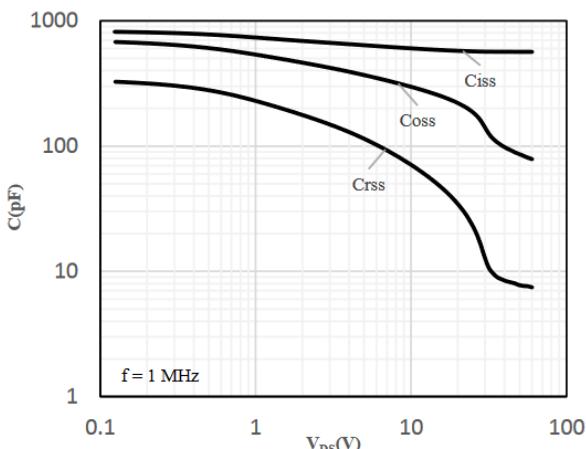
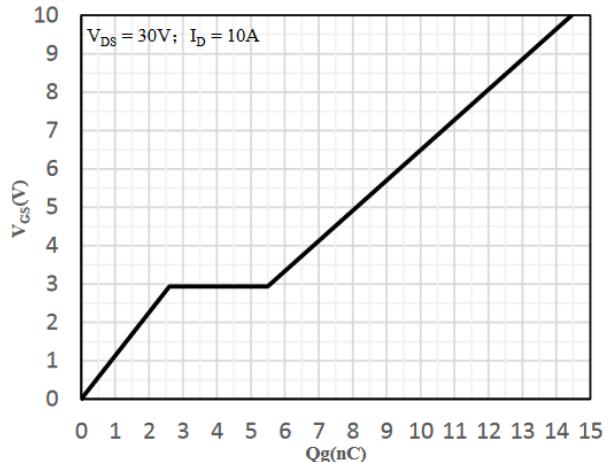


ON-resistance vs. gate-source voltage



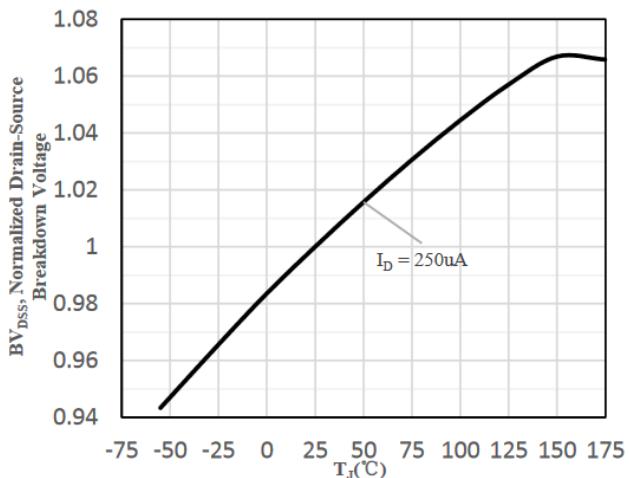
Body-diode characteristics



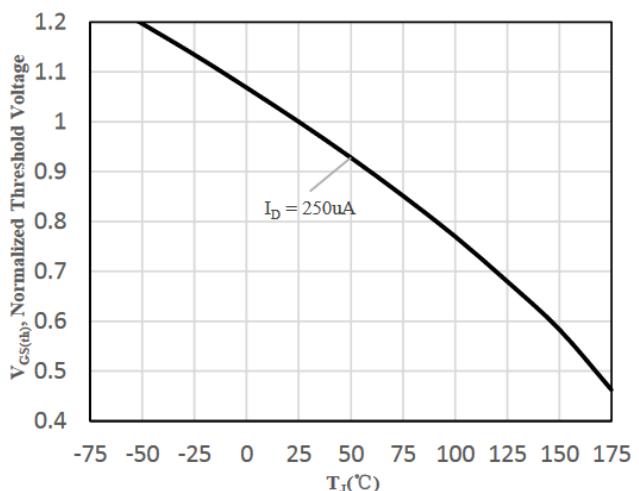
Typical characteristics
Normalized ON-resistance vs. junction temperature

Transfer characteristics

Capacitance characteristics

Gate-charge characteristics


Typical characteristics

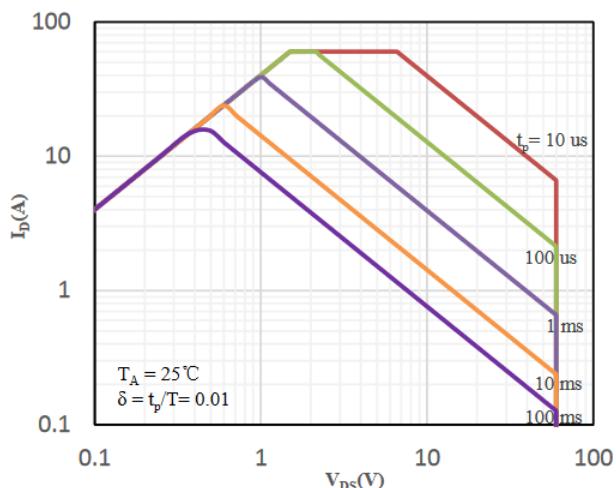
Normalized breakdown voltage vs junction temperature



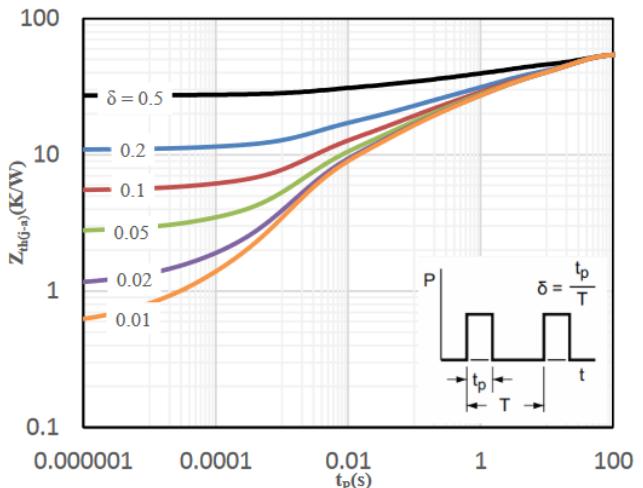
Normalized $V_{GS(th)}$ vs junction temperature

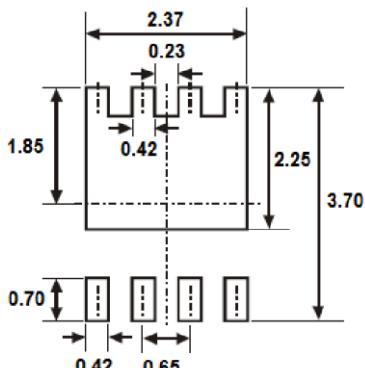


Safe operation area



Maximum transient thermal impedance



Suggested soldering pad layout

PDFN3x3-8L
Ordering information

Part Number	Marking	Package	Shipping Quantity	Dimensions
AKS250N06T-3D8	250N06T	PDFN3x3-8L	5000 pcs / reel	---

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